EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L57	5177	(composite with thermal with expansion with coefficient)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:36
L58	204	(composite with thermal with expansion with coefficient) same electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:36
L59	20	(composite with thermal with expansion with coefficient) same electrode same power	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:37
L60	10	(composite with thermal with expansion with coefficient) same electrode same power same semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:37
L61	1	(composite with thermal with expansion with coefficient) same electrode same power same semiconductor same (silicon or si)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:38
L62	1	(composite with thermal with coefficient) same electrode same power same semiconductor same (silicon or si)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:38
L63	820	(composite with thermal with coefficient) same (silicon or si)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:38
L64	59	(composite with thermal with coefficient) same (silicon or si) and (semiconductor near5 power)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:39
L65	17	(composite with thermal with coefficient) same (silicon or si) and (semiconductor near5 power) and fiber	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:39

L66	21	(composite with thermal with coefficient) same (silicon or si) and (semiconductor near5 power) and (fiber or graphite)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:40
L67	11	(composite with thermal with coefficient) same (silicon or si) and (semiconductor near5 power) and fiber and graphite	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:40
L68	7	(composite with thermal with coefficient) same (silicon or si) and (semiconductor near5 power) and fiber and graphite.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:40
L69	7	(composite near10 thermal with coefficient) same (silicon or si) and (semiconductor near5 power) and fiber and graphite.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:41
L70	7	(composite near10 thermal near10 coefficient) same (silicon or si) and (semiconductor near5 power) and fiber and graphite.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:41
L71	6	(composite near10 thermal near10 coefficient) near10 (silicon or si) and (semiconductor near5 power) and fiber and graphite.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:45
L72	7	(composite near10 thermal near10 coefficient) near10 (silicon or si) and (semiconductor near5 power) and fiber and graphite	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:46
L73	12	(composite near10 thermal near10 coefficient) near10 (semiconductor or silicon or si) and (semiconductor near5 power) and fiber and graphite	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:49
L74	6	(composite near10 thermal near10 coefficient) near10 (semiconductor or silicon or si) and (semiconductor near5 power) and (fiber near10 graphite)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:49
L75	6	(composite near10 thermal near10 coefficient) near10 (semiconductor or silicon or si) and (semiconductor near5 power) and (fiber with graphite)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:49

L76	7	(composite near10 thermal near10 coefficient) near10 (semiconductor or silicon or si) and (semiconductor near10 power) and (fiber with graphite)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:50
L77	67	((composite near10 thermal near10 coefficient) near10 (semiconductor or silicon or si)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:53
L78	66	((composite with thermal near2 coefficient) near10 (semiconductor or silicon or si)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:53
L79	114	((composite with thermal near2 coefficient) with (semiconductor or silicon or si)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:53
L80	7	((composite with thermal near2 coefficient) with (semiconductor or silicon or si)).clm. and (power near2 semiconductor).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:54
L81	27	((composite with thermal near2 coefficient) with (semiconductor or silicon or si)).clm. and (power near2 semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:54